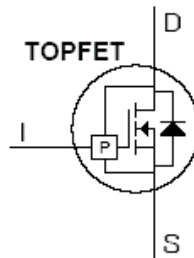
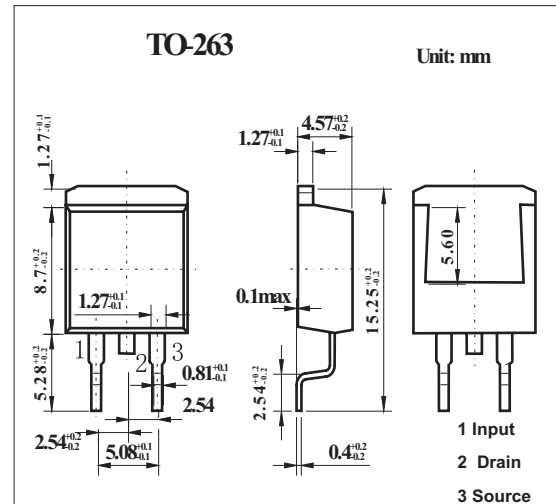


Logic level TOPFET

KUK128-50DL

■ Features

- TrenchMOS output stage
- Current limiting
- Overload protection
- Overtemperature protection
- Protection latched reset by input
- 5 V logic compatible input level
- Control of output stage and supply of overload protection circuits derived from input
- Low operating input current permits direct drive by micro-controller
- ESD protection on all pins
- Overvoltage clamping for turn off of inductive loads

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|--|------------|-------------|------------------|
| Continuous drain source voltage | V_{DS} | 50 | V |
| Continuous drain current $V_{IS} = 5\text{ V}$; $T_{mb} = 25^\circ\text{C}$ | I_D | selflimited | A |
| Continuous drain current $V_{IS} = 5\text{ V}$; $T_{mb} \leq 125^\circ\text{C}$ | I_D | 8 | A |
| Continuous input current | I_I | -5 to 5 | mA |
| Repetitive peak input current $t_p \leq 1\text{ ms}$ | I_{IRM} | -10 to 10 | mA |
| Total power dissipation $T_{mb} \leq 25^\circ\text{C}$ | P_D | 40 | W |
| Storage temperature | T_{stg} | -55 To 175 | $^\circ\text{C}$ |
| Continuous junction temperature normal operation | T_j | 150 | $^\circ\text{C}$ |
| Case temperature during soldering | T_{sold} | 260 | $^\circ\text{C}$ |
| Electrostatic discharge capacitor voltage * | V_C | 2 | kV |

* $C = 250\text{ pF}$; $R = 1.5\text{ k}\Omega$

KUK128-50DL

■ Electrical Characteristics Ta = 25°C

| Parameter | Symbol | Testconditons | Min | Typ | Max | Unit |
|---|----------------------|---|-----|-----|-----|------------------|
| Non-repetitive clamping energy | EDSM | $I_{DM} = 8\text{ A}; V_{DD} \leq 20\text{ V}; T_{mb} \leq 25^\circ\text{C}$ | | | 100 | mJ |
| Repetitive clamping energy | EDRM | $I_{DM} = 8\text{ A}; V_{DD} \leq 20\text{ V}; T_{mb} \leq 95^\circ\text{C}; f = 250\text{ Hz}$ | | | 20 | mJ |
| Drain source voltage | V_{DS} | $4\text{ V} \leq V_{IS} \leq 5.5\text{ V}$ | 0 | | 35 | V |
| Drain-source clamping voltage | $V_{(CL)DSS}$ | $V_{IS} = 0\text{ V}; I_D = 10\text{ mA}$ | 50 | | | V |
| | | $V_{IS} = 0\text{ V}; I_{DM} = 2\text{ A}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.01$ | 50 | 60 | 70 | V |
| Drain source leakage current | I_{DSS} | $V_{DS} = 40\text{ V}$ | | | 100 | μA |
| | | $V_{DS} = 40\text{ V}; T_{mb} = 25^\circ\text{C}$ | | 0.1 | 10 | μA |
| Drain-source resistance | $R_{DS(ON)}$ | $V_{IS} \geq 4.4\text{ V}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.01; I_{DM} = 3\text{ A}$ | | | 190 | m Ω |
| | | $V_{IS} \geq 4.4\text{ V}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.01; I_{DM} = 3\text{ A}; T_{mb} = 25^\circ\text{C}$ | | 68 | 100 | m Ω |
| | | $V_{IS} \geq 4\text{ V}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.01; I_{DM} = 3\text{ A}$ | | | 200 | m Ω |
| | | $V_{IS} \geq 4\text{ V}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.01; I_{DM} = 3\text{ A}; T_{mb} = 25^\circ\text{C}$ | | 72 | 105 | m Ω |
| Drain current limiting | I_D | $V_{DS} = 13\text{ V}; V_{IS} = 5\text{ V}; T_{mb} = 25^\circ\text{C}$ | 8 | 12 | 16 | A |
| | | $V_{DS} = 13\text{ V}; 4.4\text{ V} \leq V_{IS} \leq 5.5\text{ V}$ | 6 | | 18 | A |
| | | $V_{DS} = 13\text{ V}; 4\text{ V} \leq V_{IS} \leq 5.5\text{ V}$ | 5 | | 18 | A |
| Overload power threshold | $P_{D(TO)}$ | device trips if $P_D > P_{D(TO)}$; $V_{IS} = 5\text{ V}; T_{mb} = 25^\circ\text{C}$ | 20 | 55 | 80 | W |
| Characteristic time | T_{DSC} | | 200 | 350 | 600 | μs |
| Threshold junction temperature | $T_{j(TO)}$ | | 150 | 170 | | $^\circ\text{C}$ |
| Input threshold voltage | $V_{IS(TO)}$ | $V_{DS} = 5\text{ V}; I_D = 1\text{ mA}$ | 0.6 | | 2.4 | V |
| | | $V_{DS} = 5\text{ V}; I_D = 1\text{ mA}; T_{mb} = 25^\circ\text{C}$ | 1.1 | 1.6 | 2.1 | V |
| Input supply current | I_{IS} | normal operation; $V_{IS} = 5\text{ V}$ | 100 | 220 | 400 | μA |
| | | normal operation; $V_{IS} = 4\text{ V}$ | 80 | 195 | 330 | |
| Input supply current | I_{ISL} | protection latched; $V_{IS} = 5\text{ V}$ | 200 | 400 | 650 | |
| | | protection latched; $V_{IS} = 3\text{ V}$ | 130 | 250 | 430 | |
| Protection reset voltage | V_{ISR} | reset time $t_r \geq 100\text{ }\mu\text{s}$ | 1.5 | 2 | 2.9 | V |
| Latch reset time | t_{lr} | $V_{IS1} = 5\text{ V}, V_{IS2} < 1\text{ V}$ | 10 | 40 | 100 | μs |
| Input clamping voltage | $V_{(CL)IS}$ | $I_I = 1.5\text{ mA}$ | 5.5 | | 8.5 | V |
| Input series resistance to gate of power MOSFET | R_{IG} | $I_I = 1.5\text{ mA}; T_{mb} = 25^\circ\text{C}$ | | 33 | | k Ω |
| Turn-on delay time | $t_{d\text{ on}}$ | $V_{IS} = 5\text{ V}$ | | 8 | 20 | μs |
| Rise time | t_r | | | 20 | 50 | |
| Turn-off delay time | $t_{d\text{ off}}$ | $V_{IS} = 0\text{ V}$ | | 25 | 70 | |
| Fall time | t_f | | | 16 | 40 | |
| Junction to mounting base | $R_{th\text{ j-mb}}$ | | | 2.5 | 3.1 | K/W |
| Junction to ambient | $R_{th\text{ j-a}}$ | minimum footprint FR4 PCB | | 50 | | K/W |